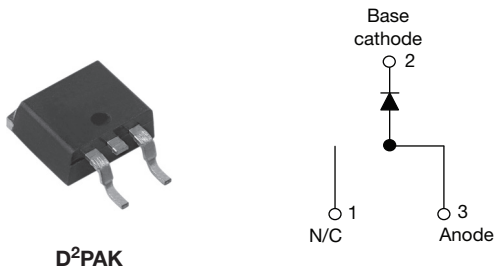


## High Performance Schottky Rectifier, 15 A



### FEATURES

- 150 °C  $T_J$  operation
- Very low forward voltage drop
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### DESCRIPTION

The VS-15TQ060SPbF Schottky rectifier has been optimized for very low forward voltage drop, with moderate leakage. The proprietary barrier technology allows for reliable operation up to 150 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

PRODUCT SUMMARY	
Package	D <sup>2</sup> PAK
$I_{F(AV)}$	15 A
$V_R$	60 V
$V_F$ at $I_F$	0.56 V
$I_{RM}$ max.	45 mA at 125 °C
$T_J$ max.	150 °C
Diode variation	Single die
$E_{AS}$	6 mJ

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Rectangular waveform	15	A
$V_{RRM}$		60	V
$I_{FSM}$	$t_p = 5 \mu s$ sine	1000	A
$V_F$	15 A <sub>pk</sub> , $T_J = 125$ °C	0.56	V
$T_J$	Range	-55 to +150	°C

VOLTAGE RATINGS			
PARAMETER	SYMBOL	VS-15TQ060SPbF	UNITS
Maximum DC reverse voltage	$V_R$	60	V
Maximum working peak reverse voltage	$V_{RWM}$		

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward current See fig. 5	$I_{F(AV)}$	50 % duty cycle at $T_C = 104$ °C, rectangular waveform		15	A
Maximum peak one cycle non-repetitive surge current See fig. 7	$I_{FSM}$	5 $\mu s$ sine or 3 $\mu s$ rect. pulse	Following any rated load condition and with rated $V_{RRM}$ applied	1000	A
		10 ms sine or 6 ms rect. pulse		260	
Non-repetitive avalanche energy	$E_{AS}$	$T_J = 25$ °C, $I_{AS} = 1.5$ A, $L = 11.5$ mH		6	mJ
Repetitive avalanche current	$I_{AR}$	Current decaying linearly to zero in 1 $\mu s$ Frequency limited by $T_J$ maximum $V_A = 1.5 \times V_R$ typical		1.50	A



ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop See fig. 1	$V_{FM}^{(1)}$	15 A	$T_J = 25\text{ }^\circ\text{C}$	0.62	V
		30 A		0.82	
		15 A	$T_J = 125\text{ }^\circ\text{C}$	0.56	
		30 A		0.71	
Maximum reverse leakage current See fig. 2	$I_{RM}^{(1)}$	$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{Rated } V_R$	0.80	mA
		$T_J = 125\text{ }^\circ\text{C}$		45	
Maximum junction capacitance	$C_T$	$V_R = 5 V_{DC}$ (test signal range 100 kHz to 1 MHz), $25\text{ }^\circ\text{C}$		720	pF
Typical series inductance	$L_S$	Measured lead to lead 5 mm from package body		8.0	nH
Maximum voltage rate of change	dV/dt	Rated $V_R$		10 000	V/ $\mu$ s

**Note**

(1) Pulse width < 300  $\mu$ s, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$			-55 to +150	$^\circ\text{C}$
Maximum thermal resistance, junction to case	$R_{thJC}$	DC operation See fig. 4		3.25	$^\circ\text{C/W}$
Typical thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, smooth and greased		0.50	
Approximate weight				2	g
				0.07	oz.
Mounting torque	minimum			6 (5)	kgf · cm (lbf · in)
	maximum			12 (10)	
Marking device		Case style D <sup>2</sup> PAK		15TQ060S	

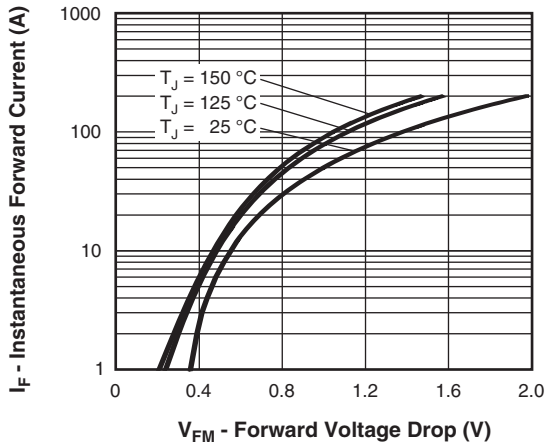


Fig. 1 - Maximum Forward Voltage Drop Characteristics

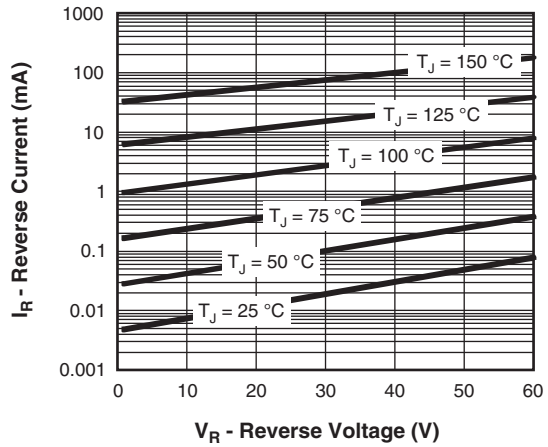


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

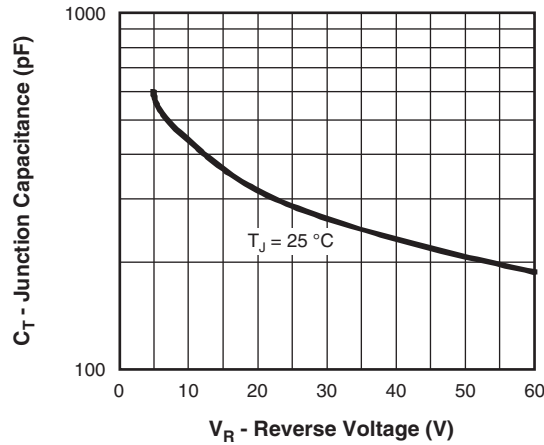


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

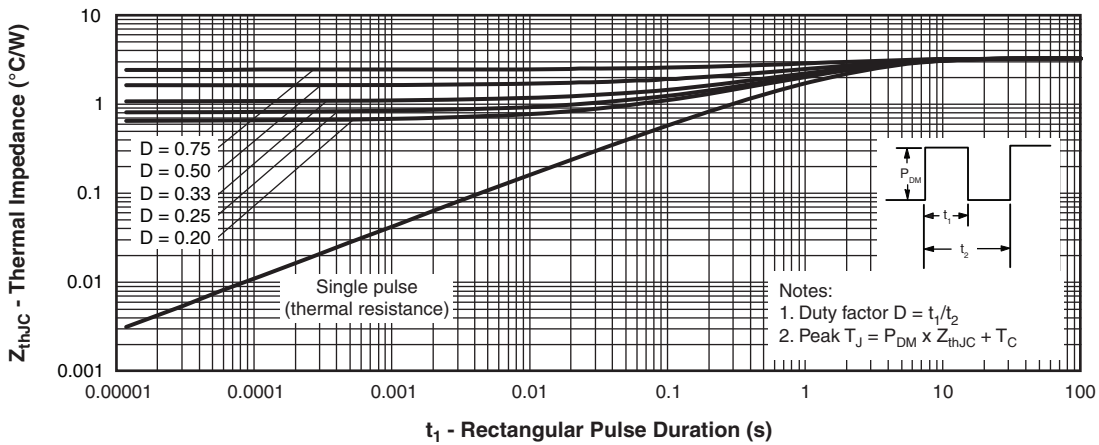


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

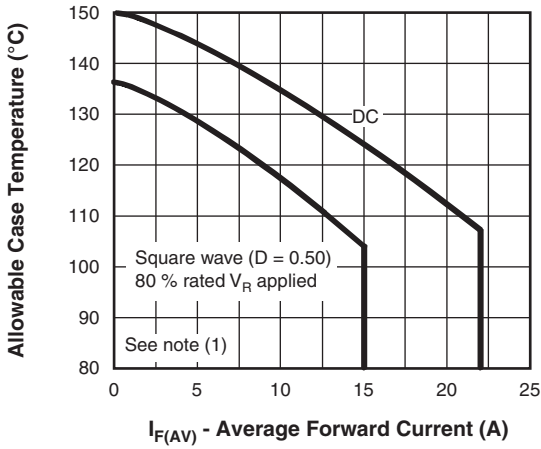


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

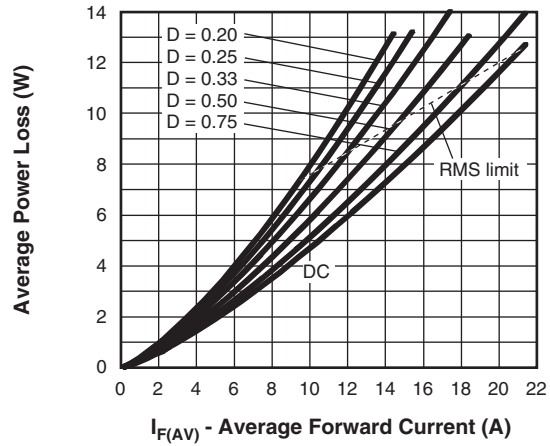


Fig. 6 - Forward Power Loss Characteristics

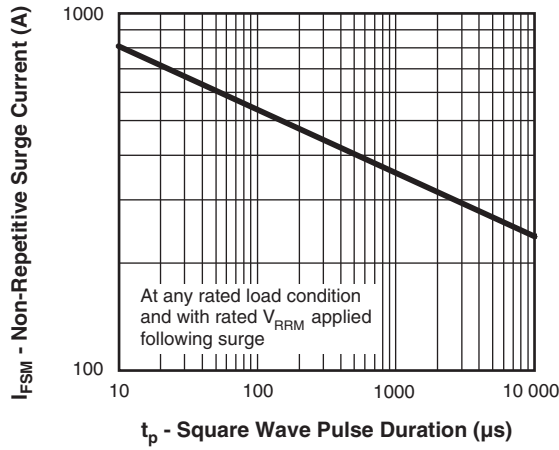


Fig. 7 - Maximum Non-Repetitive Surge Current

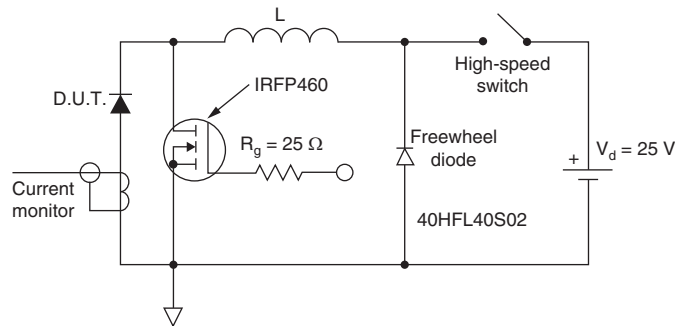


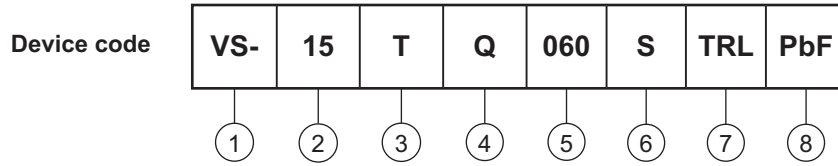
Fig. 8 - Unclamped Inductive Test Circuit

**Note**

- (1) Formula used:  $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$ ;
- $P_d$  = Forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);
- $P_{d_{REV}}$  = Inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1} = 80\%$  rated  $V_R$



ORDERING INFORMATION TABLE



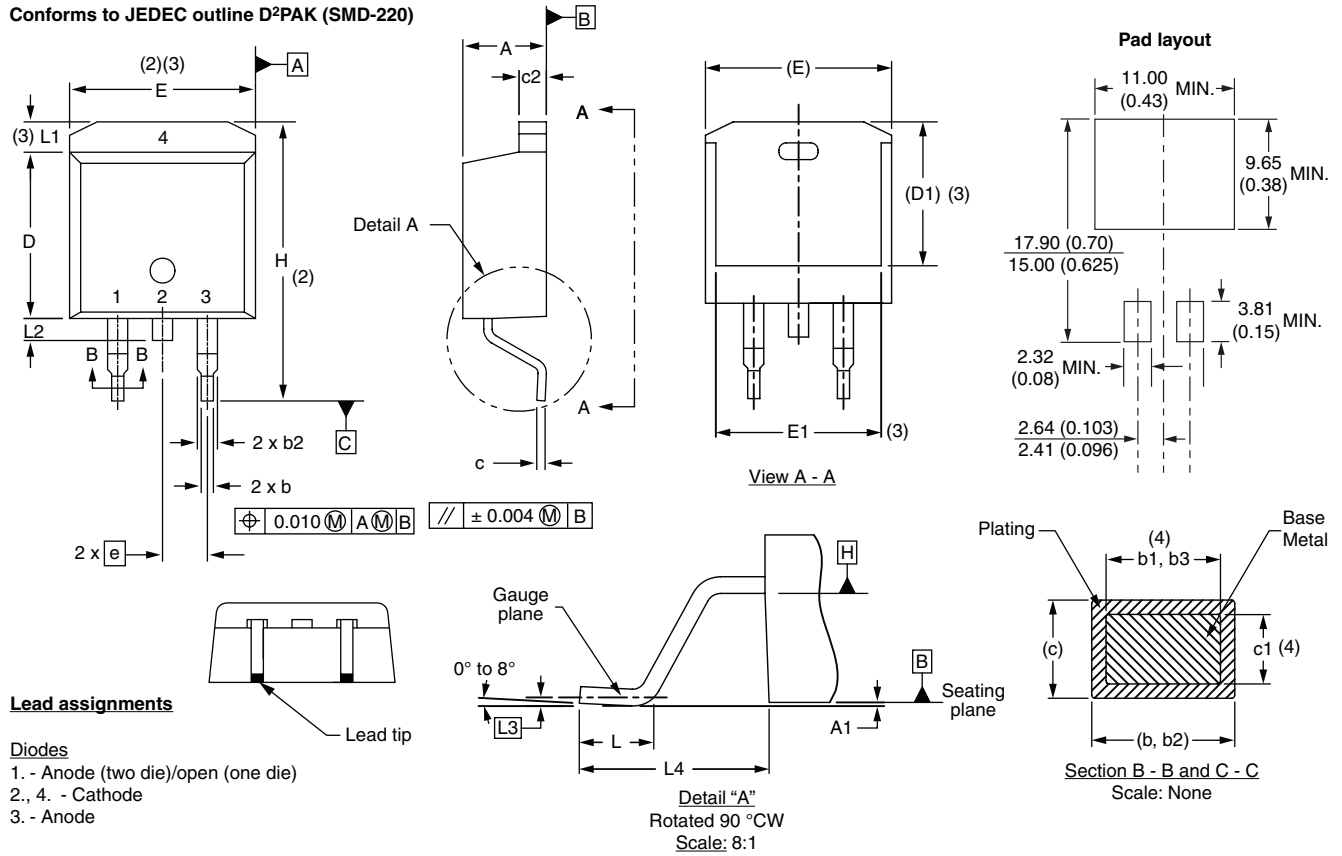
- 1** - Vishay Semiconductors product
- 2** - Current rating (15 A)
- 3** - Circuit configuration: T = TO-220
- 4** - Schottky "Q" series
- 5** - Voltage rating (060 = 60 V)
- 6** - S = D<sup>2</sup>PAK
- 7** -
  - None = tube (50 pieces)
  - TRL = tape and reel (left oriented)
  - TRR = tape and reel (right oriented)
- 8** - PbF = lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95014">www.vishay.com/doc?95014</a>
Part marking information	<a href="http://www.vishay.com/doc?95008">www.vishay.com/doc?95008</a>
Packaging information	<a href="http://www.vishay.com/doc?95032">www.vishay.com/doc?95032</a>
SPIICE model	<a href="http://www.vishay.com/doc?95600">www.vishay.com/doc?95600</a>

## D<sup>2</sup>PAK, TO-262

### DIMENSIONS FOR D<sup>2</sup>PAK in millimeters and inches

Conforms to JEDEC outline D<sup>2</sup>PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

#### Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch

- (7) Outline conforms to JEDEC outline TO-263AB

## DIMENSIONS FOR TO-262 in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

**Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline



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